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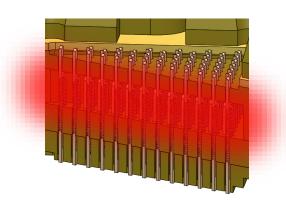
UNICON[™] TEST CONTACTING SOLUTION

https://www.jf-technology.com

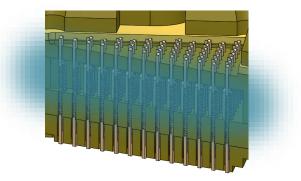
Features & Benefits

01	Unibody Design/Homogenous Material Low Resistance Barrier Precision measurements, Test consistency	
02	One Piece Structure and Relay Low Resistance barrier Better Signal Integrity Fast frequency response (TDR) Unibody Design/Homogenous Material	
03	Flat Sheet Boundless Design Self cleaning, avoids localized heating and melting	
04	Unique Socket Construction Rigid Embodiment, Performance consistency	
05	2D-Spring Controlled Inductance/Impedance Application friendly	
06	Temperature Assisted Socket Design Tri-Temp Capability, Sustainable performance	
07	Advanced Contact Finishing – [ACF] ⁺ Low to High frequency applications. Longer MTBA, MTBE, Sustainability of specification	

Unicon Performance



TCC: Thermal Conditioning Channel (150°C)



TCC: Thermal Conditioning Channel (- 40°C)

Mechanical Specifications	Unicon *
Pin Uncompressed Height (mm)	3.44
Pin Compliance (mm)	0.15 ~ 0.20
Force (grams)	10 ~ 20
Number of Insertion- Housing	> 1M
Number of Insertion- Pin	300k ~ 500k
Operating Temperature (°C)	- 40 to 150
Socket/Module Material	Torlon® 5030 or equivalent
Pin Material	Special Alloy
Plating	Gold-Plated

Electrical Specifications	Unicon *
Inductance (nH)	< 1.0
Capacitance (pF)	< 0.5
S21 (Insertion Loss/Bandwidth)	- 1 dB @ 26 GHz
S11 (Return Loss/Bandwidth)	- 20 dB @ 5 GHz
S41 (Crosstalk/Bandwidth)	- 20dB @ 27 GHz
Contact DC Resistance (m Ω)	≤ 70
Current Carrying Capacity (A)	~ 1.5

* Disclaimer:

 Above data are development data and is subjected to change at any time based on improvements and other reasons

 Simulated results are general specifications based on 0.30mm pitching showing the highest bandwidth number

Above data based on 0.10 mm pin thickness

Note * : The stated specifications are based on JF Microtechnology's Laboratory Test; the results may vary subjected to the test environment conditions. Information furnished by JF Microtechnology is believed to be accurate and reliable. However, no responsibility is assumed by JF Microtechnology for its use, nor for any infringements of patents or other rights of third parties that may result from its use. Specifications subject to change without notice. No license is granted by implication or otherwise under any patent or patent rights of JF Microtechnology. Trademarks and registered trademarks are the property of their respective owners.

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